

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Do Young LEE	08/18/2009
Byoung Su LEE	08/18/2009
RECEIVING PARTY DATA	
Name:	SILICONFILE TECHNOLOGIES INC.
Street Address:	9F, Yewon Bldg, 75-1, Yangjae-dong, Seocho-gu
City:	Seoul
State/Country:	REPUBLIC OF KOREA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12528603
CORRESPONDENCE DATA	
Fax Number:	(202)659-8822
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	2026598000
Email:	jpark@kgmrlaw.com
Correspondent Name:	Jae Y. Park
Address Line 1:	Kile, Goekjian, Reed & McManus, PLLC
Address Line 2:	1200 New Hampshire Ave. NW, Suite 570
Address Line 4:	Washington, DISTRICT OF COLUMBIA 20036
ATTORNEY DOCKET NUMBER:	GUA-0088-LE
NAME OF SUBMITTER:	JAE Y. PARK
Total Attachments: 2 source=AssmtGUA0088#page1.tif source=AssmtGUA0088#page2.tif	

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PATENT
REEL: 023144 FRAME: 0557

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

Insert Name(s)
and Address(es) WHEREAS, LEE, Do Young of 402-1002 Hansol Apt. 102 Jungja-dong, Bundang-gu, Seongnam-si,
of Inventor(s) Kyeonggi-do and LEE, Byoung Su of 5-9, Munsu-dong, Yeosu-si, Jeollanam-do, Korea
(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in

Insert Title
of Invention FINGERPRINT RECOGNITION DEVICE AND USER AUTHENTICATION METHOD FOR CARD
INCLUDING THE FINGERPRINT RECOGNITION DEVICE

which claims priority to [KOREA] Application No(s). 10-2007-0026463, filed on March 19, 2007, and
for which the undersigned is (are) about to file an application for Letters Patent of the United States; and

Insert Name
of Assignee WHEREAS, SILICONFILE TECHNOLOGIES INC.

Insert Address
of Assignee of 9F, Yewon Bldg, 75-1, Yangjae-dong, Seocho-gu, Seoul, Korea

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of
acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that
may be granted therefor in the United States of America and in any foreign countries.

NOW, THEREFORE, to all whom it may concern, be it known that, for good and valuable consideration
paid to the undersigned, the receipt of which is hereby acknowledged, the undersigned has (have) sold,
assigned and transferred, and by these presents does sell, assign and transfer unto the Assignee the full and
exclusive right to the said invention in the United States of America, its territories, dependencies and
possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be
granted therefor in the United States of America, its territories, dependencies and possessions, and in any
and all foreign countries:

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or
terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any
continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments
in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be
declared concerning this application or continuation, division, conversion or reissue thereof or Letter
Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in
obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be
necessary in connection with claims or provisions of the International Convention for the Protection of
Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned declare that all statements made herein of his own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Name of Inventor: LEE, Do Young, Signature D. Young Lee, Date Aug 18, 2009

Name of Inventor: LEE, Byoung Su, Signature [Signature], Date August 18, 2009

Name of Inventor: _____, Signature _____, Date _____